HEL-00017-N1-GP

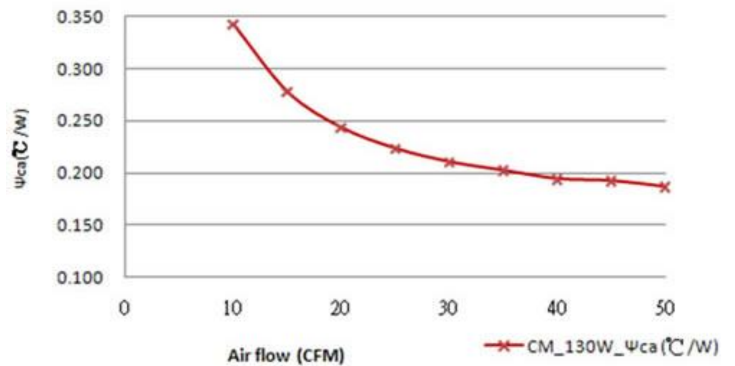
Thermal and Mechanical Spec

Thermal performance for 130W CPU

HSK Assembly Weight: 528 g

CPU Loading: 65 lbf

Performance Curve



Application

LGA 1366/1356 (Socket B/B2) M3

Test result:

	130W
Flow (CFM)	Rca (℃/W)
10	0.3428
15	0.2779
20	0.2434
25	0.2233
30	0.2103
35	0.2021
40	0.194
45	0.1922
50	0.1864

Component Specifications

Application System	2U Form Factor Passive Solution
Material	Aluminum Fin + Copper Base + Heat pipe Diameter 6 × 2
Dimension	88.9L × 88.9W × 63H mm
Fin	Thick=0.4mm, Pitch=1.55mm, 57 fin
Thermal interface Material	Shin Etsu 7783 (34 × 34 mm)

*All readings are typical values at rated voltage.

*Specifications are subjected to change without notice.

Safety

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